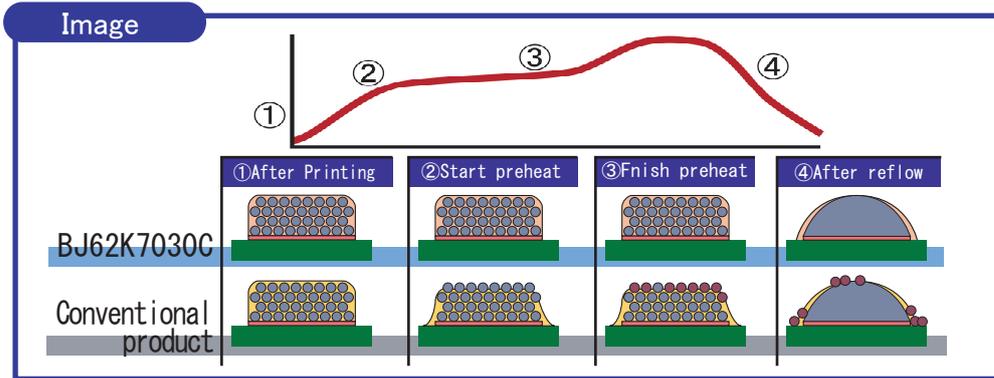


SOLDIM BJ62K7030C

Heat-resistant realization in high temperature

In conventional product, flux contained in solder paste is flowed by reflow heating. And powder which aren't covered by flux is oxidized. It means not good wettability.

However, We have adjusted viscosity of flux in heating and improved heat-resistant realization. It means flux isn't flowed and solder powder isn't oxidized. And This BJ62K7030C has good wettability.



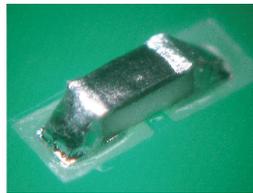
Wetability test

Flux contained in BJ62K7030C has good thermo-stability. In preheat and reflow, flux isn't flowed. Solder powder isn't oxidized and wettability is good.

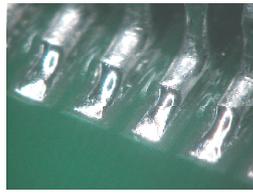
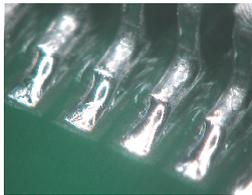
Preheat 150°C

Preheat 170°C

0603 Chip



0.5mm Pitch QFP

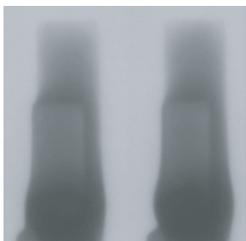


Void test

BJ62K7030C has good wettability and less voids caused by de-wetting.

BJ62K7030C

Conventional product



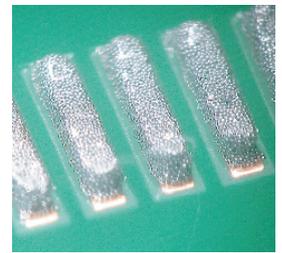
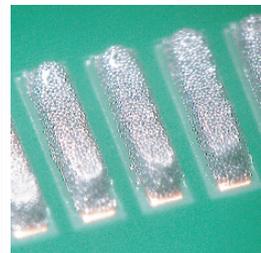
Printing test

BJ62K7030C has good printability.

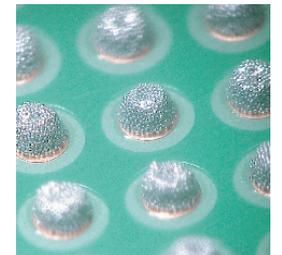
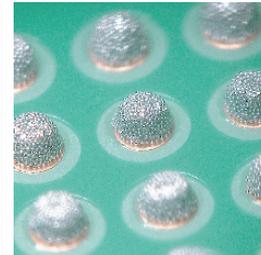
初期

5枚目

0.4 ピッチ



0.3 ドット

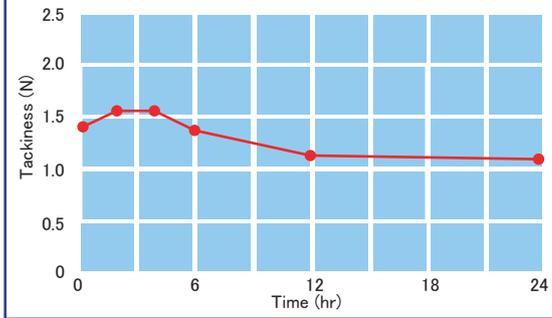


条件・印圧: 45N
・印刷速度: 30mm/s

Tackiness Test

Tackiness of BJ62K7030C is stable over long time.

Tackiness Test



Test condition: 25°C

Characteristic Data

Characteristic data of BJ62K7030C is shown below.

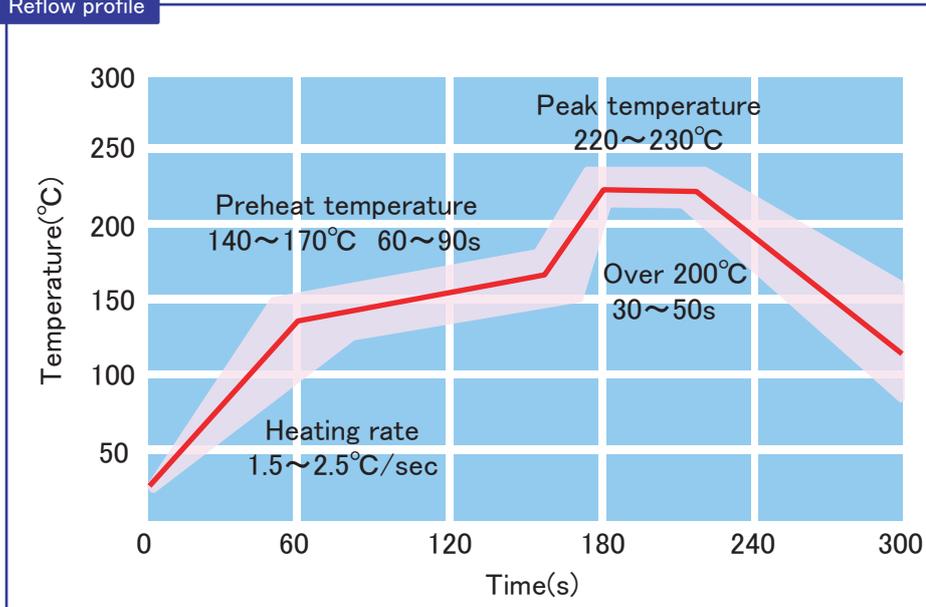
Product name	BJ62K7030C
Alloy composition(%)	Sn: 62, Ag: 2, Pb: Balance
Melting point(°C)	179~190
Powder particle size(μm)	38~25
Halide content(%)	0.12※ ₁
Flux contents(%)	9.5
Spreading ratio(%)	93
Copper plate corrosion test	Pass
Viscosity(Pa·s)	215
Tackiness test	>24Hr
Storage stability	6 months (Under 10°C)

※ Above values are typical value.

※₁ This solder paste contain non-ionic halide activator.

Recommendable temperature profile

Reflow profile



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